

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Yen-Hao Shih	09/20/2005
Shih-Chin Lee	09/20/2005
Jung-Yu Hsieh	09/20/2005
Erh-Kun Lai	09/20/2005
Kuang Yeu Hsieh	09/20/2005
RECEIVING PARTY DATA	
Name:	Macronix International Co., Ltd. (A Taiwanese Corporation)
Street Address:	No. 16, Li-Hsin Road
Internal Address:	Science Based Industrial Park
City:	Hsinchu
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11209875
CORRESPONDENCE DATA	
Fax Number:	(215)965-1210
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	2159651240
Email:	aettelman@akingump.com
Correspondent Name:	Aaron R. Ettelman [681939-87US]
Address Line 1:	One Commerce Square
Address Line 2:	2005 Market Street, Suite 2200
Address Line 4:	Philadelphia, PENNSYLVANIA 19103-7013
ATTORNEY DOCKET NUMBER:	681939-87US
NAME OF SUBMITTER:	Renee Conti

CH \$40.00 11209875

Total Attachments: 3

source=assignment#page1.tif

source=assignment#page2.tif

source=assignment#page3.tif

**ASSIGNMENT
(PATENT APPLICATION)**

WHEREAS, we, (“ASSIGNORS”):

<u>Inventor</u>	<u>Citizenship</u>	<u>Address</u>
Yen-Hao Shih	Taiwanese	4F., No. 42, Changsing Street Changhua City, Changhua County 500 Taiwan (R.O.C.)
Shih-Chin Lee	Taiwanese	No. 16-2, Jhongheng Road Siluo Township, Yunlin County 648 Taiwan (R.O.C.)
Jung-Yu Hsieh	Taiwanese	3F., No. 49, Lane 27, Zihyou Road Hsinchu City 300 Taiwan (R.O.C.)
Erh-Kun Lai	Taiwanese	No. 14, Lane 411, Youyuan N. Road Longjing Shiang, Taichung County 434 Taiwan (R.O.C.)
Kuang Yeu Hsieh	Taiwanese	No. 10, Singhai Street Jhubei City, Hsinchu County 302 Taiwan (R.O.C.)

having invented a certain new and useful invention entitled:

**METHODS OF FORMING CHARGE-TRAPPING DIELECTRIC LAYERS FOR
SEMICONDUCTOR MEMORY DEVICES**

for which a United States patent application is to be filed or has been filed on August 23, 2005 under U.S. Patent Application No. 11/209,875; and

WHEREAS, (“ASSIGNEE”):

Macronix International Co., Ltd.
(A Taiwanese Corporation)
No. 16, Li-Hsin Road
Science Based Industrial Park
Hsinchu, Taiwan, R.O.C.

is desirous of acquiring the entire right, title and interest in and to the invention throughout the United States and the world, and all right, title and interest in, to and under any and all Letters Patent of the United States and all countries throughout the world;

FOR GOOD and VALUABLE CONSIDERATION, the full receipt and sufficiency of which are hereby acknowledged, ASSIGNORS, intending to be legally bound, do hereby:

AUTHORIZE said ASSIGNEE, or its representatives to insert above the filing date and application number of the application when these are known;

SELL, ASSIGN, TRANSFER and CONVEY to ASSIGNEE the whole and entire right, title and interest for the United States and its possessions and territories and all foreign countries in and to the invention which is disclosed in the above-identified patent application, and, in and to any and all patent applications related thereto including, but not limited to, all provisionals, non-provisionals, divisionals, continuations, continuations-in-part, substitutes, reexaminations, reissues and all other applications for patent which have been or shall be filed in the United States and all foreign countries on the invention; all original, reissued and reexamined patents and extensions thereof which have been or shall be issued in the United States and all foreign countries on the invention to the full end of the term or terms for which the patent(s) may be granted, as fully and entirely as the same would have been held by the undersigned ASSIGNOR(S) had this Assignment not been made; and specifically including all rights of priority created by the above patent application under any treaty, convention or law relating thereto;

AUTHORIZE and REQUEST the issuing authority to issue any and all United States and foreign patents granted on the invention to ASSIGNEE;

WARRANT and REPRESENT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by ASSIGNORS, and that the full right to convey the same as herein expressed is possessed by ASSIGNORS;

AGREE and UNDERTAKE, when requested and at the expense of ASSIGNEE, to carry out in good faith the intent and purpose of this Assignment, ASSIGNORS will execute all non-provisionals, divisionals, continuations, continuations-in-part, substitutes, reexaminations, reissues, and all other patent applications on the invention; execute all lawful oaths, declarations, assignments, powers of attorney and other papers; communicate to ASSIGNEE all facts known to ASSIGNORS relating to the invention and the history thereof; and generally do everything possible which ASSIGNEE shall consider desirable for vesting title to the invention in ASSIGNEE, and for securing, maintaining and enforcing proper patent protection for the invention; all without further compensation to ASSIGNORS;

TO BE BINDING on the heirs, assigns, representatives and successors of ASSIGNORS and extending to the successors, assigns, and nominees of ASSIGNEE.

Sep. 20, 2005
Date

Yeh-Hao Shih
Yeh-Hao Shih

Sep. 20, 2005
Date

2005. 9. 20
Date

~~2005. 9. 20~~ ^{2005/9/20}
Date

2005/9/20
Date

Shih-Chin Lee
Shih-Chin Lee

Jung-Yu Hsieh
Jung-Yu Hsieh

~~Jung-Yu Hsieh~~ Erh-Kun Lai
Erh-Kun Lai

Kuang-Yeu Hsieh
Kuang Yeu Hsieh